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# **TECHNICAL DATA SHEET**

supersedes previous issue dated 14/09/99

## AX2004/00

## **BINDER FOR WATERBORNE AND SOLVENT-BASED STAINS**

Area of use:	Picture frames, kitchen doors, profiles.
Method of use:	Spray gun.
Thinning:	With water or DX0986/00 or DX1131/00 thinners.

### **Technical characteristics**

Solids content (%):	20 ± 1
Specific gravity (kg/l):	$0.970 \pm 0.030$
Viscosity (DIN 4 at 20°C):	19" ± 4"
Shelf-life (months):	15

#### **General characteristics**

AX2004/00 is a film-forming binder to be used together with stains to provide more uniform poremarking and to allow better wiping of the wet stain (by hand or automatically).

The quantity of AX2004/00 to be added to the stain varies according to requirements, although the following is a general guideline:

 Stain (XM8000/XX)
 1 part

 AX2004/00
 1-2 parts

 Thinner
 3-10 parts

For solvent based stains suitable thinners are DX1131/00 (when maximum drying speed is required), or DX0986/00 (slow drying) when wiping is required (as with oak). Water can used as a thinner, although this obviously gives much longer drying times (wait at least eight hours before overcoating).

N.B.: Data provided on this Technical Data Sheet correspond to our best knowledge and experience. We assure consistency on the chemical-physical characteristics of our products, within the tolerance limits specified on our Technical Data Sheets. Responsibility of final result of product application is fully up to the users, who shall make sure that the product corresponds to their own needs with regard to application system, to substrates used as well as to working conditions.